



Specialists in precision laser machining and drilling of difficult applications



Over 30 years of experience in multilayer ceramics: Alumina (HTCC), Aluminum Nitride, BeO and LTCC



Thermal adhesives offering unmatched thermal conductivities, exceeding most common solders.



Novel and effective custom electronic packaging design and fabrication for a wide range of applications; Extensive library of engineering tools for custom modeling services.



Southern California based, short to medium run LTCC alumina substrate and package manufacturer



Combining Plated Copper Metallization with multilayer Thick Films for Custom Metallized Ceramic Substrates, Chip Carriers and Hermetic Packages.



Specialized sputtering and vapor deposition. Thin film metallization and optical coatings, development and manufacture of custom semiconductor and MEMs devices.



Custom lightweight thermal management solutions, based on a family of Spray Formed Controlled Expansion ("CE") aluminum alloys.



Manufacturer of high reliability hermetic packages and windows for RF/Microwave, Fiber Optic, Detector, Power and Hybrid applications. Custom designs or choose from our thousands of standard tools.



Leader in the development and supply of advanced diamond thin-film and free-standing diamond deposition products and services.

APA also maintains relationships with several sources of high value solutions for **ORGANIC SUBSTRATES CONTRACT MICROELECTRONIC ASSEMBLY SERVICES**

Contact us today to determine the best option.

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